

MOS FIELD EFFECT TRANSISTOR **2SK3570**

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3570 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

FEATURES

- •4.5V drive available.
- •Low on-state resistance,

 $R_{DS(on)1} = 12 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 10 \text{ V, ID} = 24 \text{ A)}$

•Low gate charge

 $Q_G = 23 \text{ nC TYP.}$ ($V_{DD} = 16 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 48 \text{ A}$)

- •Built-in gate protection diode
- •Surface mount device available

★ ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3570	TO-220AB
2SK3570-S	TO-262
2SK3570-ZK	TO-263
2SK3570-Z	TO-220SMD Note

Note TO-220SMD package is produced only in Japan.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vos = 0 V)	VDSS	20	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I _{D(DC)}	±48	Α
Drain Current (pulse) Note	ID(pulse)	±160	Α
Total Power Dissipation (T _A = 25°C)	P _{T1}	1.5	W
Total Power Dissipation (Tc = 25°C)	P _{T2}	29	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +150	°C

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version. Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

Note PW \leq 10 μ s, Duty Cycle \leq 1%



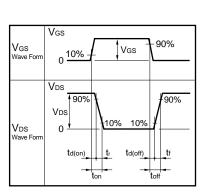
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ELECTRICAL CHARACTERISTICS (TA = 25°C)

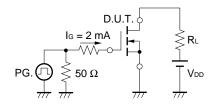
Characteristics	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Zero Gate Voltage Drain Current	Ipss	V _{DS} = 20 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	Vgs = ±20 V, Vps = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5		2.5	V
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 24 A	8.0			S
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, ID = 24 A		8.2	12	mΩ
	R _{DS(on)2}	Vgs = 4.5 V, ID = 15 A		12.3	22	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		930		pF
Output Capacitance	Coss	Vgs = 0 V		360		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		250		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10 V, I _D = 24 A		13		ns
Rise Time	tr	Vgs = 10 V		20		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		39		ns
Fall Time	t f	1		14		ns
Total Gate Charge	Q _G	VDD = 16 V		23		nC
Gate to Source Charge	Qgs	Vgs = 10 V		4		nC
Gate to Drain Charge	Q _{GD}	ID = 48 A		7		nC
Body Diode Forward Voltage	V _F (S-D)	IF = 48 A, VGS = 0 V		1.1		V
Reverse Recovery Time	trr	IF = 48 A, VGS = 0 V		33		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		25		nC

★ TEST CIRCUIT 1 SWITCHING TIME

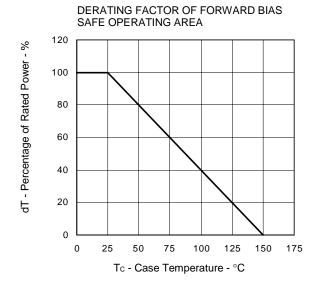
PG. \square R_{G} 0 $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$

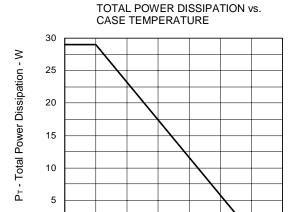


TEST CIRCUIT 2 GATE CHARGE



★查询问@A&50HAKK@商RISTICS (TA = 25°C)





75

Tc - Case Temperature - °C

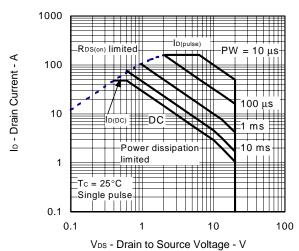
100

125

150

175

FORWARD BIAS SAFE OPERATING AREA



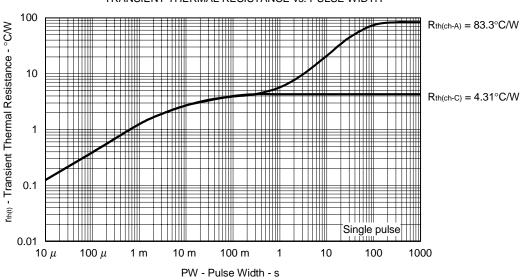
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

0

0

25

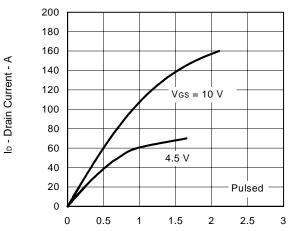
50





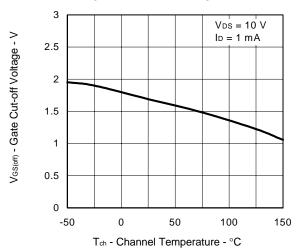
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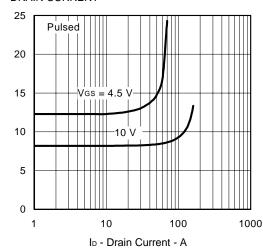


 $V_{\text{\scriptsize DS}}$ - Drain to Source Voltage - V

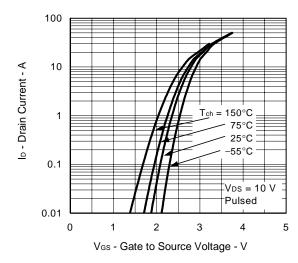
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



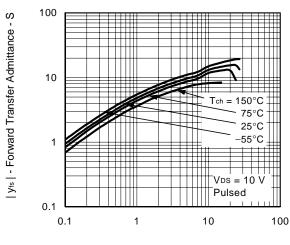
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



FORWARD TRANSFER CHARACTERISTICS

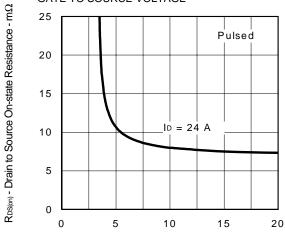


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



ID - Drain Current - A

DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



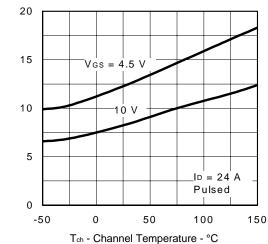
 $\ensuremath{\mathsf{V}}_{\ensuremath{\mathsf{GS}}}$ - Gate to Source Voltage - V

RDS(on) - Drain to Source On-state Resistance - m\Omega

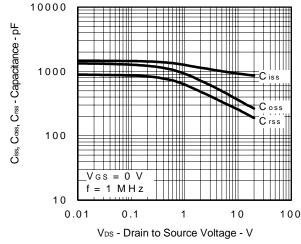
R_{DS(m)} - Drain to Source On-state Resistance - mΩ

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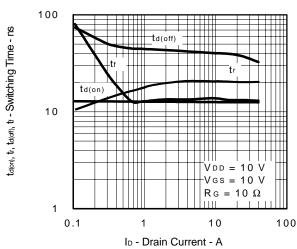




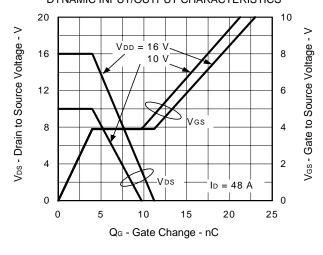
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



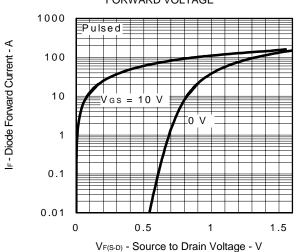
SWITCHING CHARACTERISTICS



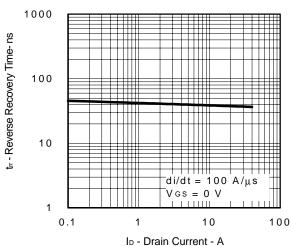
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SOURCE TO DRAIN DIODE FORWARD VOLTAGE

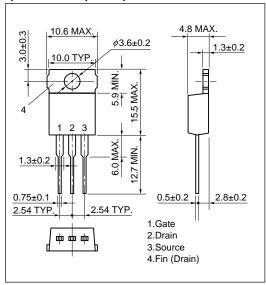


REVERSE RECOVERY TIME vs. DRAIN CURRENT

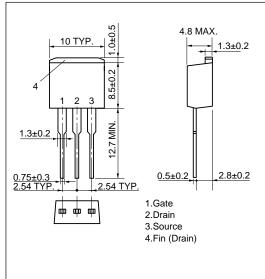


阿克尼尼斯 (Unit: mm)

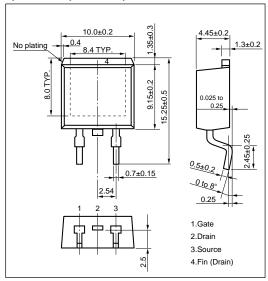
1) TO-220AB (MP-25)



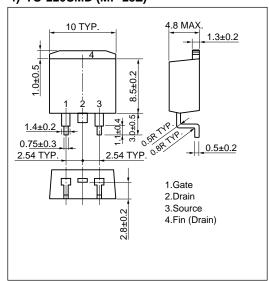
2) TO-262 (MP-25 Fin Cut)



3) TO-263 (MP-25ZK)

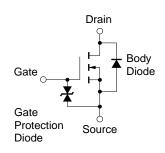


4) TO-220SMD (MP-25Z)



Note This package is produced only in Japan.

EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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